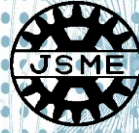




CALL FOR PAPERS

(2nd Announcement and Call for Papers)

<http://www.eng.osakafu-u.ac.jp/idecon2015>



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Objective

Bilateral collaboration between Malaysia and Japan has become increasingly important in academia as well as in industry. Originated in Malaysia, iDECON2015 will be held first time in Japan to provide an international forum for researchers, engineers, industrial practitioners of these two countries. A wide variety of topics related to design, concurrent engineering and manufacturing is accepted in iDECON2015 to facilitate sharing recent research results/trend among the participants and to explore the future directions.

Topics of interests (but not limited to)

Whole themes of design and concurrent engineering, which include CAD/CAM, CAE, Reliability in Design, Ergonomics in Design, Virtual Engineering, Concurrent Engineering, Rapid Prototyping, Reverse Engineering, Design for Automation and Intelligent Systems, Design for Mechatronics Systems, Design for Manufacturing Systems, Features Based Technology, Green Design, Sustainable design, Sustainable Materials in Design, Composite Product Design, Operation Management, Lean manufacturing, Supply Chain Management, Logistics, Material Handling, Warehousing, Global Manufacturing Management, etc.

Language

English

Venue

AWA KANKO HOTEL, Tokushima, JAPAN
<http://www.awakan.jp/acsess/index.html>

Important Date:

Apr. 30, 2015	Abstract Submission Deadline
May 15, 2015	Full Paper Submission Deadline
Jun. 15, 2015	Notification of Paper Acceptance
Jun. 30, 2015	Final Paper Submission Deadline
Sep. 6-7, 2015	Conference